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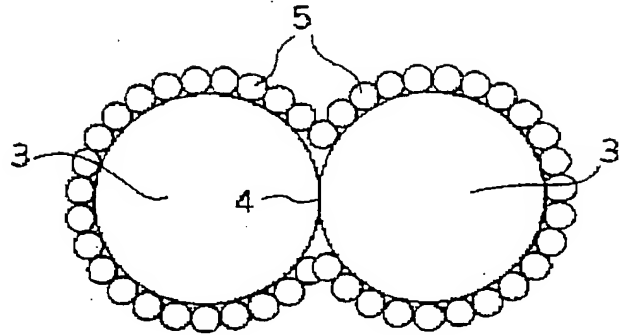
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TITLE : CONDUCTIVE PASTE, ITS
MANUFACTURE, AND PRINTED
WIRING BOARD USING THE PASTE



ABSTRACT : PROBLEM TO BE SOLVED: To reduce the material cost of a printed wiring board, and improve its connection and insulation reliability.

SOLUTION: Base metal particles 3 are coated with complexes 5 of the same metal so as to have no natural-oxidation films on its surface. When the particles 3 collect together, only the complexes 5 at corresponding contact portions 4 peel off due to the contact of the particles 3 to ensure electrical connection of the particles 3, and the complexes 5 outside the contact portions 4 remain to ensure resistance to oxidation.

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